

**2SD1833**  
Rev.F Mar.-2016

Silicon NPN transistor in a TO-220F Plastic Package.

Low V

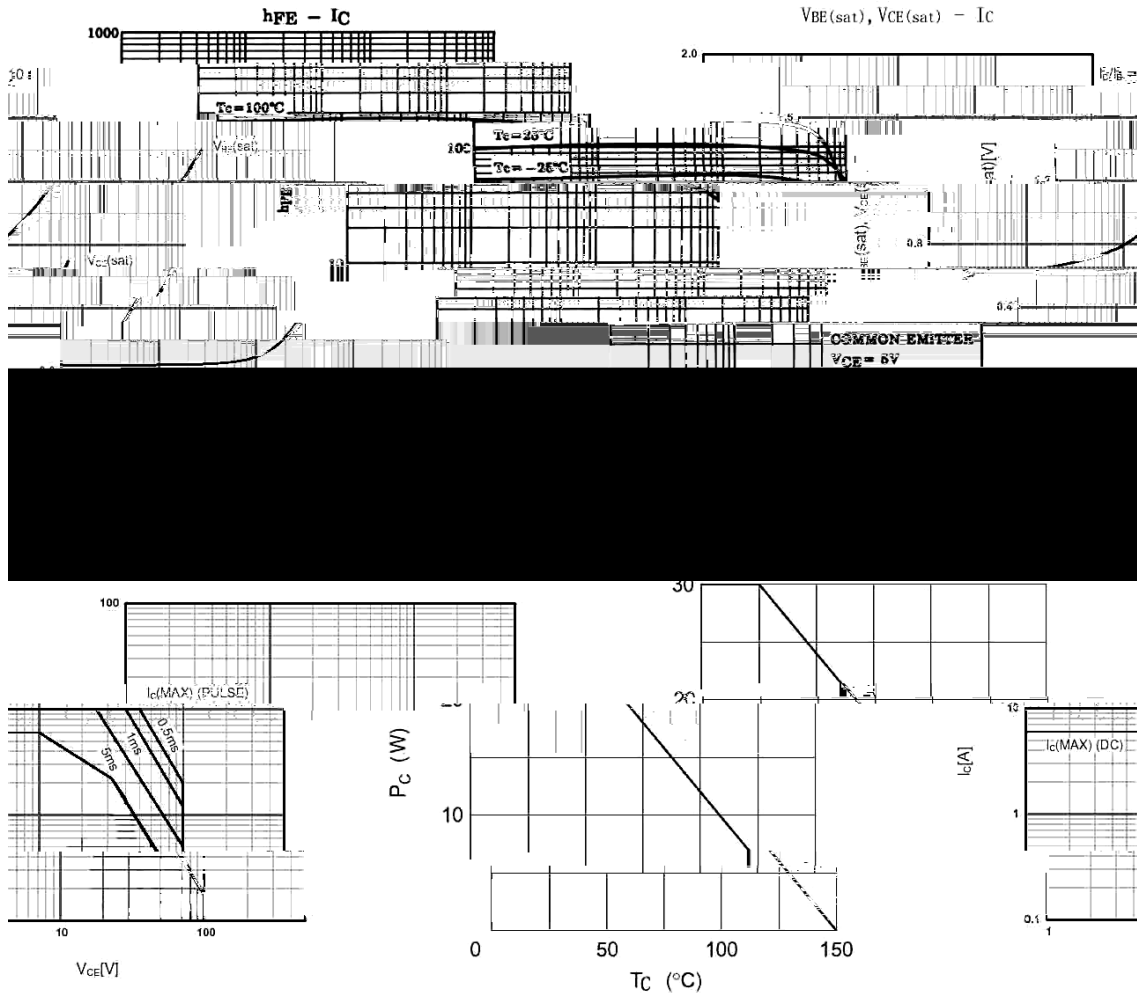
**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	100	V
Collector to Emitter Voltage	$V_{CEO}$	80	V
Emitter to Base Voltage	$V_{EBO}$	5.0	V
Collector Current - Continuous	$I_C$	7.0	A
Collector Current – Continuous(Pulse)	$I_{CP}$	10	A
Collector Power Dissipation	$P_C$	2.0	W
Collector Power Dissipation	$P_C(T_C=25 )$	30	W
Junction Temperature	$T_j$	150	
Storage Temperature Range	$T_{stg}$	-55 150	

**/ Electrical Characteristics(Ta=25 )**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=50 A$ $I_E=0$	100			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=1.0mA$ $I_B=0$	80			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=50 A$ $I_C=0$	5.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=100V$ $I_E=0$			10	A
Emitter Cut-Off Current	$I_{EBO}$	$V_{EB}=4.0V$ $I_C=0$			10	A
DC Current Gain	$h_{FE}$	$V_{CE}=5.0V$ $I_C=1.0A$	60		320	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=4.0A$ $I_B=0.4A$			1.0	V
Base to Emitter Saturation Voltage	$V_{BE(sat)}$	$I_C=4.0A$ $I_B=0.4A$			1.5	V
Transition Frequency	$f_T$	$V_{CE}=5.0V$ $f=5.0MHz$ $I_C=0.5A$		5.0		MHz
Collector output capacitance	$C_{ob}$	$V_{CB}=10V$ $f=1.0MHz$ $I_E=0A$		150		pF

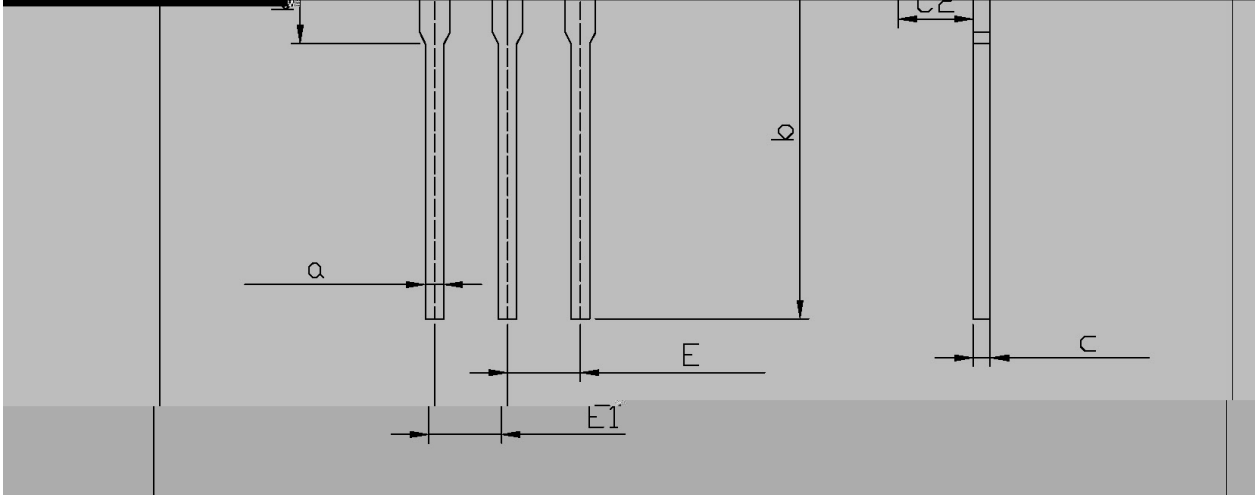
/ Electrical Characteristic Curve



/ Package Dimensions

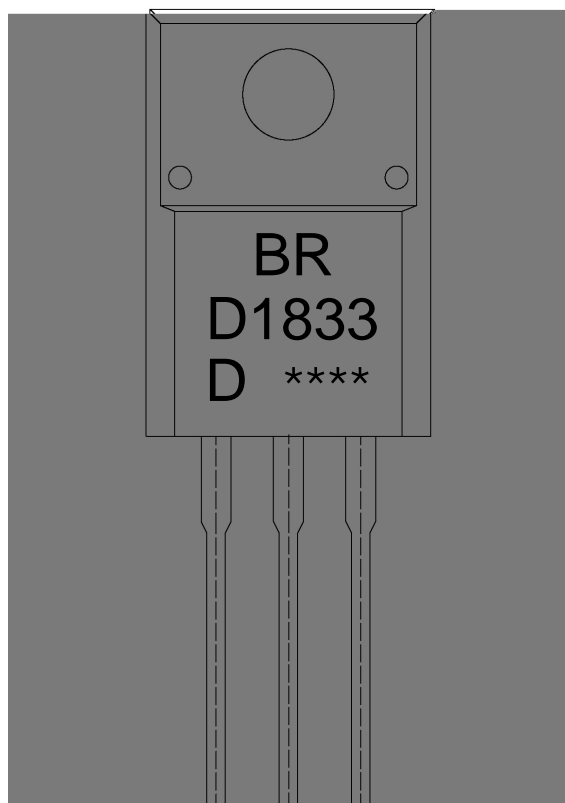
TO-220F

单位: mm



Dimensions In Millimeters			Dimensions In Millimeters		
Symbol	Min	Max	Symbol	Min	Max
C	4.3	4.7	b1	2.9	3.9
A	9.7	10.3	a	0.55	0.75
B	14.7	15.3	E	2.29	2.79
D	3.8	4.3	E1	0.5	0.75

/ Marking Instructions



Note:

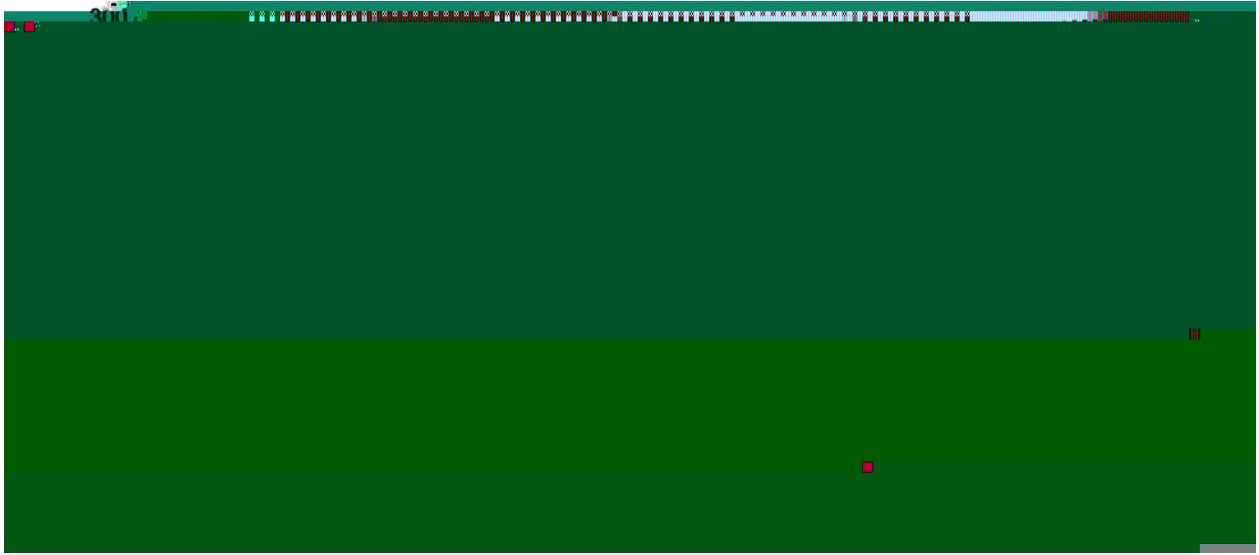
BR: Company Code.

D1833: Product Type.

D:  $h_{FE}$  Classifications Symbol

\*\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- |   |     |     |    |          |   |
|---|-----|-----|----|----------|---|
| 1 | 25  | 150 | 60 | 90sec;   | 1.Preheating:25~150 , Time:60~90sec.    |
| 2 | 255 | 5   | 5  | 0.5sec;  | 2.Peak Temp.:255 5 , Duration:5 0.5sec. |
| 3 |     |     | 2  | 10 /sec. | 3. Cooling Speed: 2~10 /sec.            |

/ Resistance to Soldering Heat Test Conditions

270 5                      10 1 sec.                      Temp.:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱
TO-220/F	200	10	2,000	5	10,000	135×190	237×172×102	560×245×195

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-220/F	50	20	1,000	5	5,000	532×31.4×5.5	555×164×50	575×290×180

/ Notices